

Engineering/Process Change Notice

ECN/PCN No.: 5015

For Manufacturer					
Product Description:	Abracon Part Number	-	☐ Documentation only	⊠ Series	
Ecliptek - Crystal	EB1	620	□ ECN	☐ Part Number	
Affected Revision:	New Revision:		⊠ EOL		
REV A		OL	Application:	☐ Safety☑ Non-Safety	
Prior to Change:		<u></u>		△ NOII-Salety	
ACTIVE					
After Change: EOL					
Cause/Reason for Change: As part of an effort to streamline our port Time Buy period	tfolio and better serve	customers, we are dis	continuing select products a	and offering a Last	
	Char	nge Plan			
Effective Date:	Additional Remarks:				
11/6/2025					
Change Declaration: Product Discontinuation					
Issued Date:	Issued By:		Issued Department:		
8/8/2025	Stephanie Lopez		Engineerir	ıg	
Approval: Thomas Culhane	Approval:	uintanilla	Approval:	200	
Engineering Director	Quality		Ying Huang Purchasing Director		
	For Abrad	con EOL only	_		
		Alternate Part Number / Part Series: ABM11AIG			
Additional Approval:	Additional Approval	•	Additional Approval:		
Customer Approval (If Applicable)					
Qualification Status:					
Note: It is considered approved if there is		☐ Not accepted customer 1 month afte	r ECN/PCN is released.		
		Customer Project:			
Company Name:	Company Representative:		Representative Signature	:	
Customer Remarks:					



Form #7020 | Rev. G | Effective: 02/22/2021 |













REGULATORY COMPLIANCE











ITEM DESCRIPTION

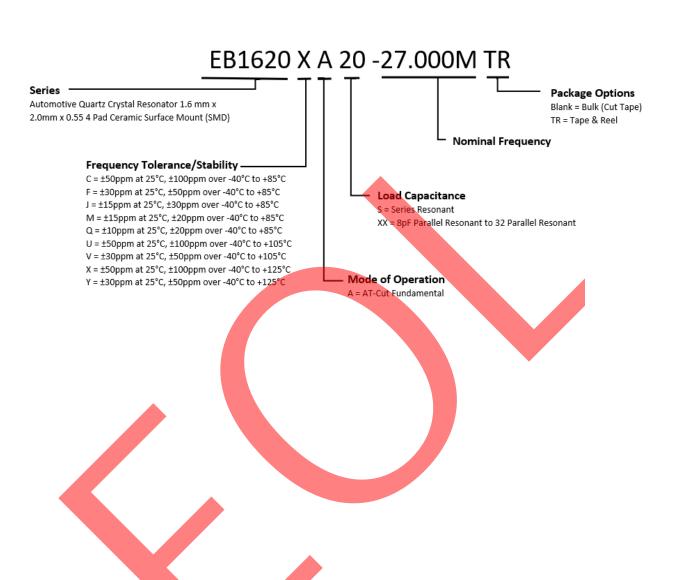
Automotive Grade Quartz Crystal Resonator 1.6mm x 2.0mm x 0.55mm 4 Pad Ceramic Surface Mount (SMD)

Nominal Frequency	16MHz to 54MHz
Frequency Tolerance/Stability	±50ppm at 25°C, ±100ppm over -40°C to +85°C ±30ppm at 25°C, ±50ppm over -40°C to +85°C ±15ppm at 25°C, ±30ppm over -40°C to +85°C ±15ppm at 25°C, ±20ppm over -40°C to +85°C ±10ppm at 25°C, ±20ppm over -40°C to +85°C ±50ppm at 25°C, ±100ppm over -40°C to +105°C ±30ppm at 25°C, ±50ppm over -40°C to +125°C ±30ppm at 25°C, ±50ppm over -40°C to +125°C
Aging at 25°C	±3ppm/year Maximum
Load Capacitance	Series Resonant, 8pF Parallel Resonant to 32pF Parallel Resonant
Shunt Capacitance	3pF Maximum
Equivalent Series Resistance	200 Ohms Maximum over Nominal Frequency of 16MHz to 19,999999MHz 120 Ohms Maximum over Nominal Frequency of 20MHz to 24,999999MHz 100 Ohms Maximum over Nominal Frequency of 25MHz to 39,999999MHz 60 Ohms Maximum over Nominal Frequency of 40MHz to 54MHz
Mode of Operation	AT-Cut Fundamental
Drive Level	1 <mark>0</mark> 0μWatts Maxim <mark>um</mark>
Spurious Response	Measured from Fo to Fo +5000ppm -3dB Minimum
Storage Temperature Range	-50°C to +150°C
Insulation Resistance	Measured at 100Vdc 500 Megaohms Minimum



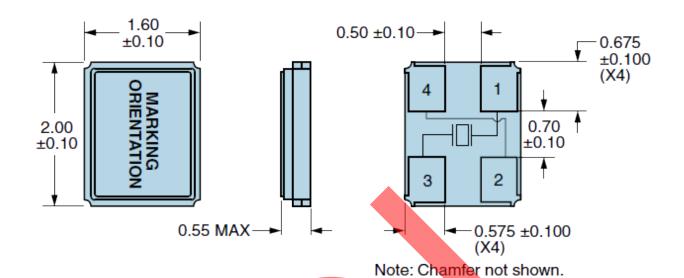


PART NUMBERING GUIDE





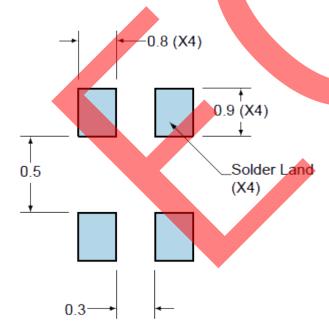
MECHANICAL DIMENSIONS



Seam Sealed

Terminal Plating Thickness: Gold (0.3 to 1.0µm) over Nickel (1.27 to 8.89µm).

SUGGESTED SOLDER PAD LAYOUT



PIN	CONNECTION
1	Crystal
2	Cover/Ground
3	Crystal
4	Cover/Ground

All Tolerances are ±0.1

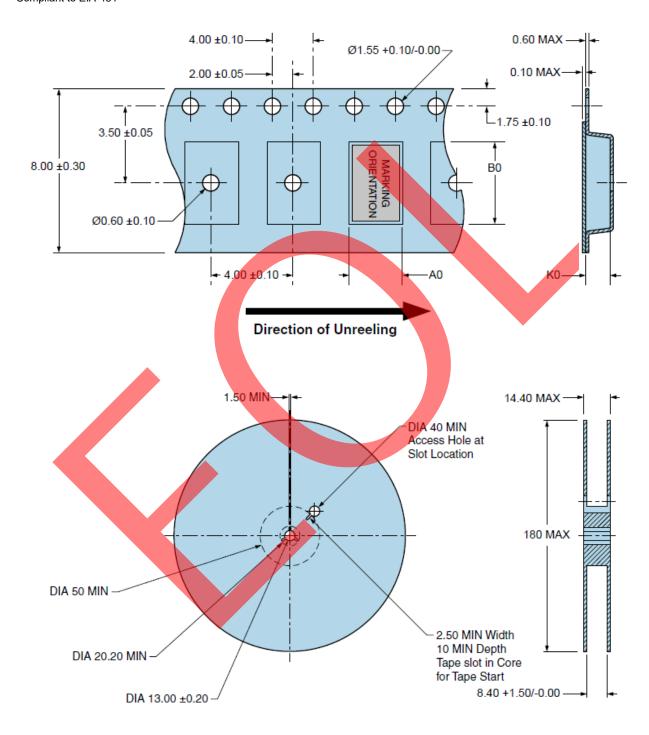
All Dimensions in Millimeters



TAPE & REEL DIMENSIONS

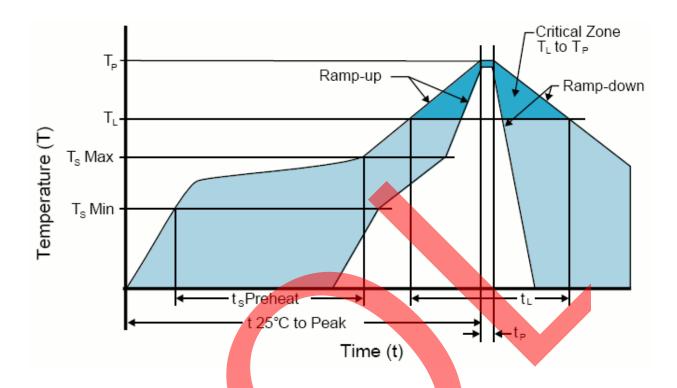
Quantity per Reel: 3,000 Units

All Dimensions in Millimeters
Compliant to EIA-481





RECOMMENDED SOLDER REFLOW METHOD



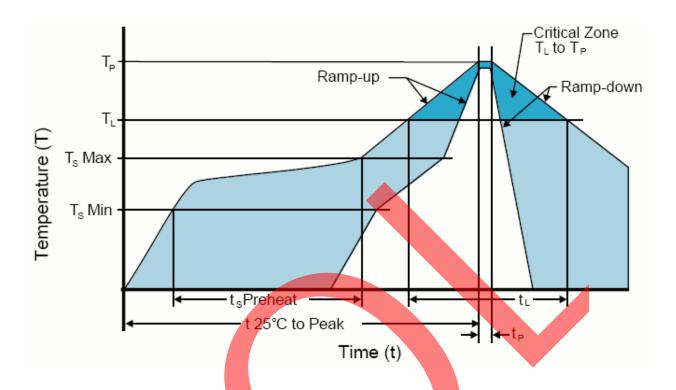
HIGH TEMPERATURE INFRARED/CONVECTION				
T _s MAX to T _L (Ramp-up Rate)	3°C/Second Maximum			
Preheat				
- Temperature Minimum (Ts MIN)	150°C			
- Temperature Typical (Ts TYP)	175°C			
- Temperature Maximum(T _s MAX)	200°C			
- Time (t _s)	60 - 180 Seconds			
Ramp-up Rate (T _L to T _P)	3°C/Second Maximum			
Time Maintained Above:				
- Temperature (T _L)	217°C			
- Time (t _L)	60 - 150 Seconds			
Peak Temperature (T _P)	260°C Maximum for 10 Seconds Maximum			
Target Peak Temperature(T _P Target)	250°C +0/-5°C			
Time within 5°C of actual peak (tp)	20 - 40 Seconds			
Ramp-down Rate	6°C/Second Maximum			
Time 25°C to Peak Temperature (t)	8 Minutes Maximum			
Moisture Sensitivity Level	Level 1			
Additional Notes	Temperatures shown are applied to body of device.			

High Temperature Manual Soldering

260°C Maximum for 5 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)



RECOMMENDED SOLDER REFLOW METHOD



LOW TEMPERATURE INCRAPED	/CONVECTION	
OW TEMPERATURE INFRARED/CONVECTION		
T _s MAX to T _L (Ramp-up Rate)	5°C/Second Maximum	
Preheat		
- Temperature Minimum (T _s MIN)	N/A	
- Temperature Typical (T _s TYP)	150°C	
- Temperature Maximum(T _s MAX)	N/A	
- Time (t _s)	30 - 60 Seconds	
Ramp-up Rate (T _L to T _P)	5°C/Second Maximum	
Time Maintained Above:		
- Temperature (T _L)	150°C	
- Time (t _L)	200 Seconds Maximum	
Peak Temperature (T _P)	245°C Maximum	
Target Peak Temperature (T _P Target)	245°C Maximum 2 Times / 230°C Maximum 1 Time	
Time within 5°C of actual peak (tp)	10 Seconds Maximum 2 Times / 80 Seconds Maximum 1 Time	
Ramp-down Rate	5°C/Second Maximum	
Time 25°C to Peak Temperature (t)	N/A	
Moisture Sensitivity Level	Level 1	
Additional Notes	Temperatures shown are applied to body of device.	

Low Temperature Manual Soldering

185°C Maximum for 10 Seconds Maximum, 2 times Maximum. (Temperatures shown are applied to body of device.)